

evs|27

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ELECTRIC VEHICLE
SYMPOSIUM & EXHIBITION.

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 Fuji Electric
Innovating Energy Technology

Ultra-Compact and Light Weight Intelligent Power Semiconductor Module for Hybrid System

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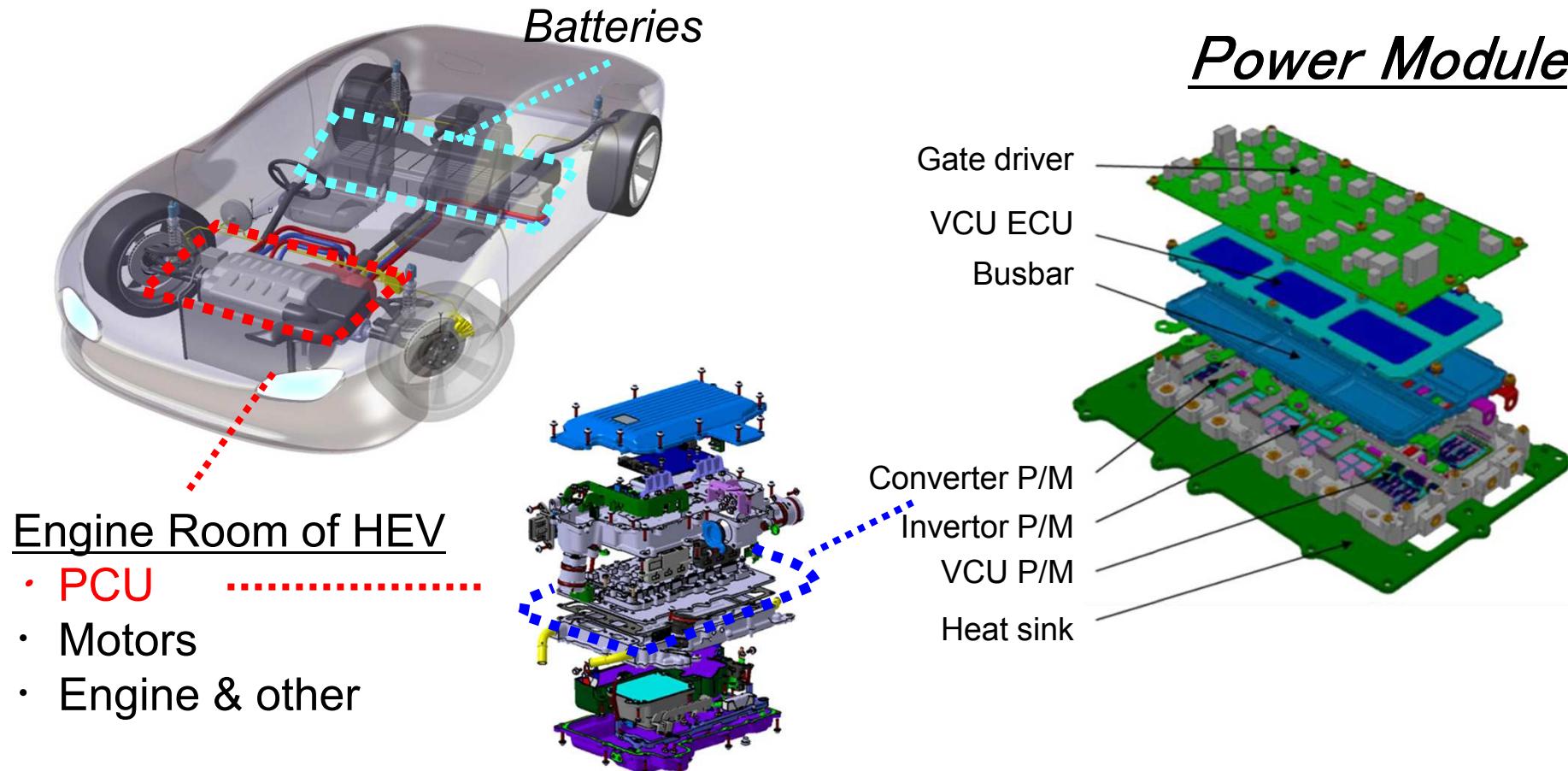
Supported by



- 1. Background of Development**
- 2. Design of Aluminum heat sink**
- 3. Development of high reliability solder material**
- 4. Conclusions**

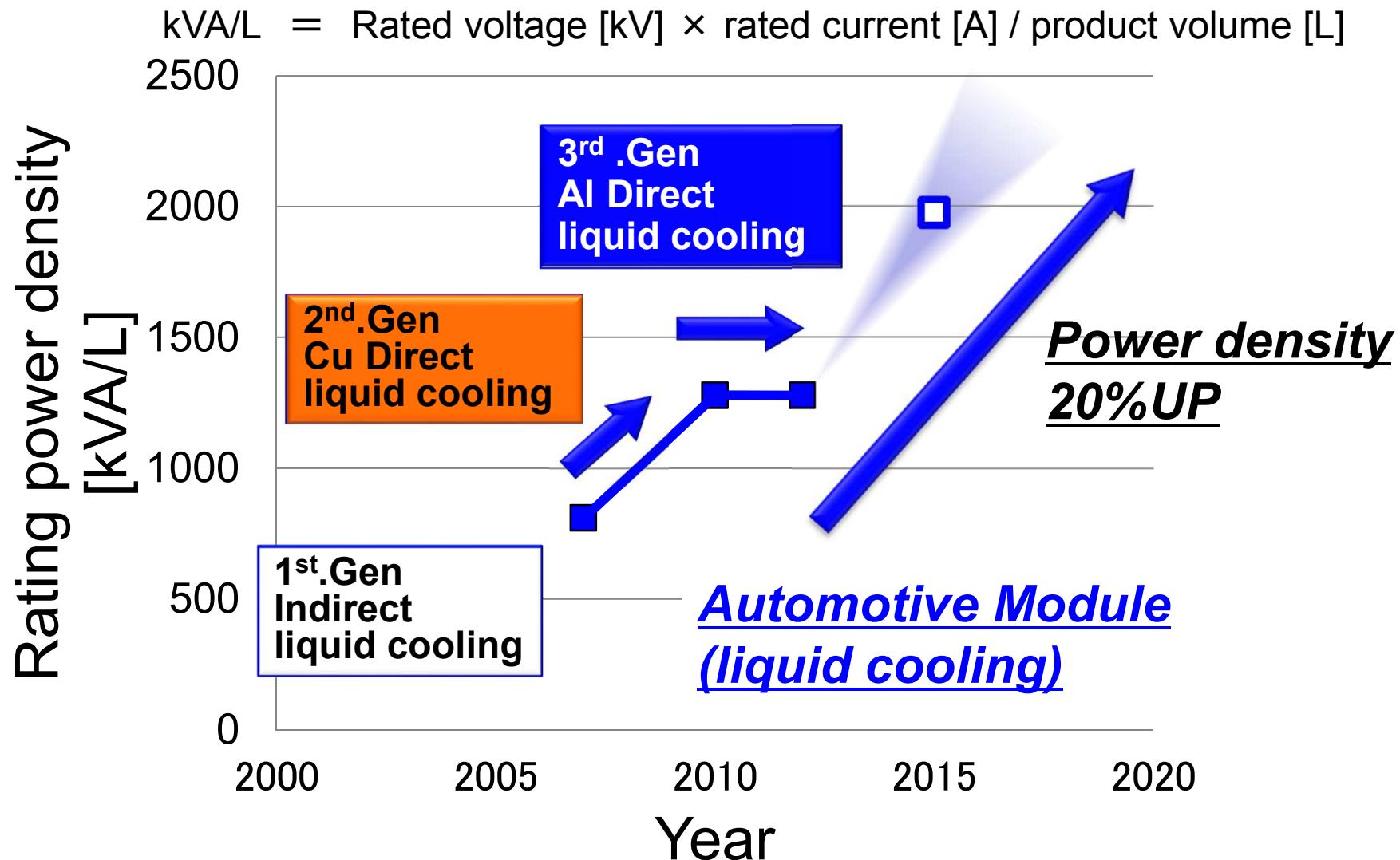
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Intelligent Power Module for Hybrid Electric Vehicles



- Requirements for power module
- 1. High Efficiency, 2. Downsizing, 3. Lightweight

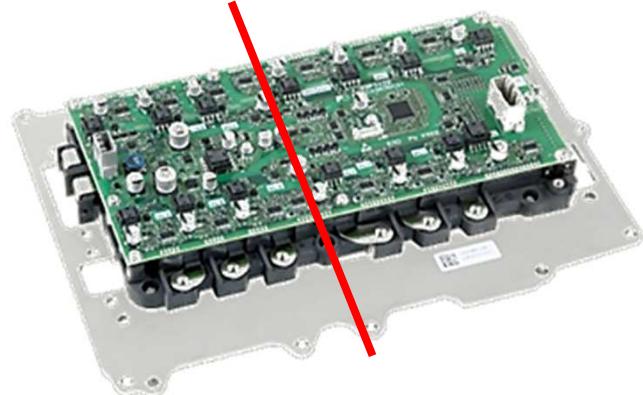
Trend of Fuji Electric Power module



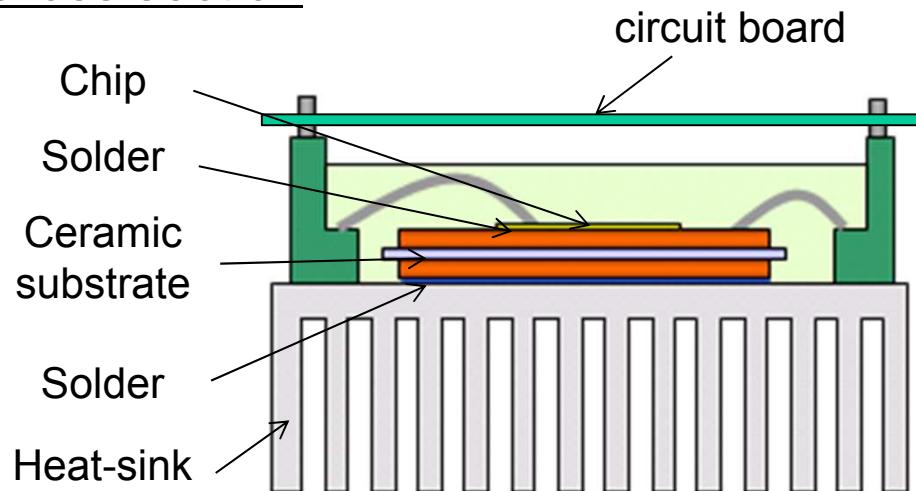
- High power density is required for automotive module
- Direct liquid cooling with aluminum fin is key technologies for 3rd gen.

Subject of Conventional Power Module Structure

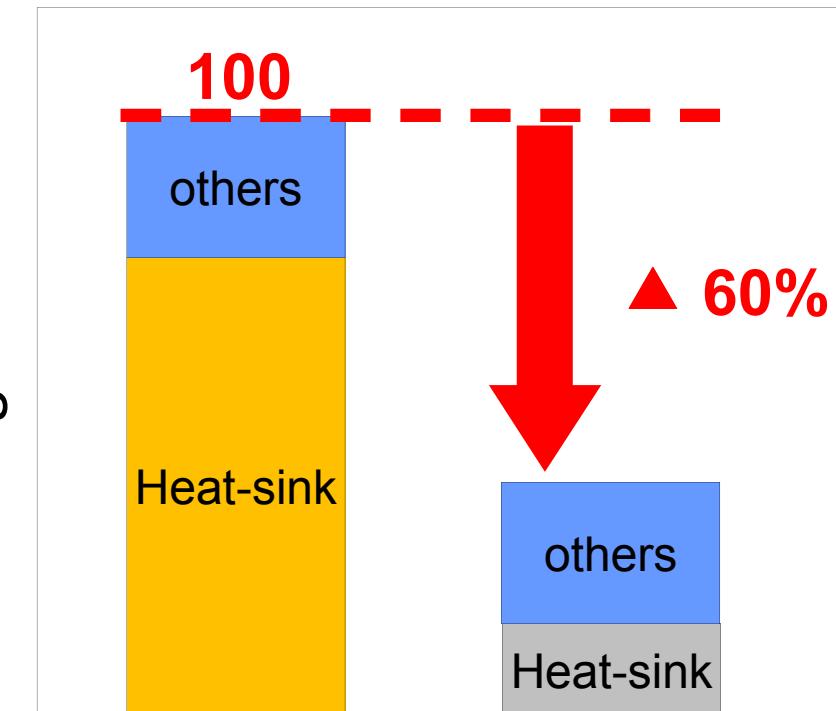
Direct liquid cooling module structure



Cross section



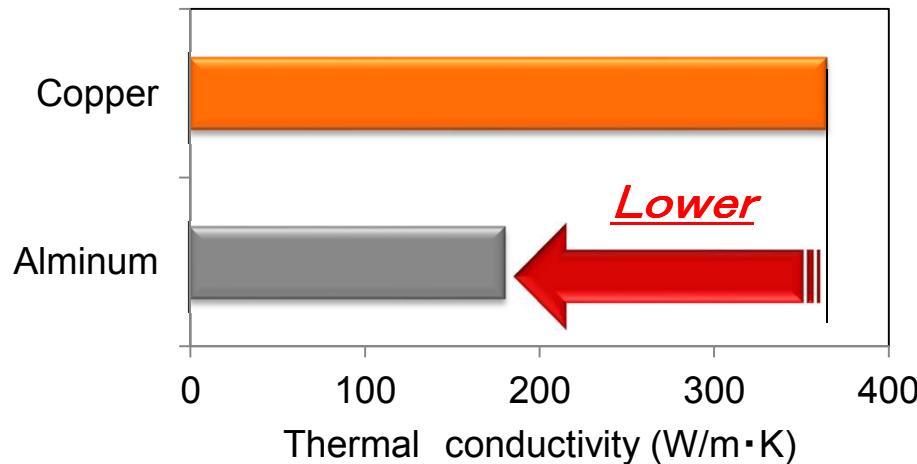
Aluminum is
➤ *Light weight*
➤ *Good corrosion resistance*



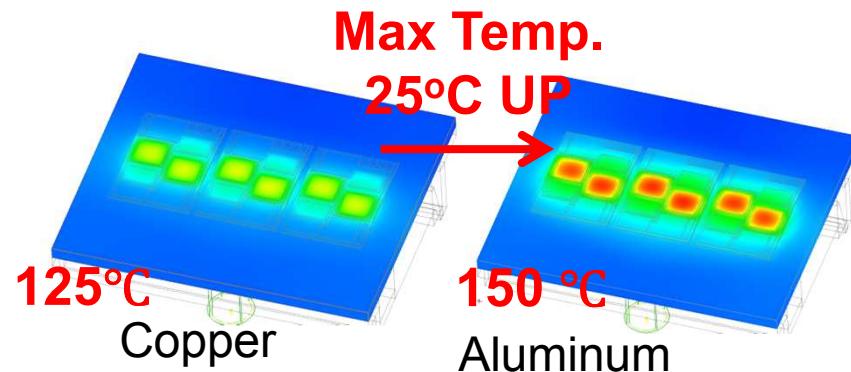
Copper
(2nd gen.)
Aluminum
Heat-sink material

■ Aluminum heat sink can reduce module weight by 60%

I. Low thermal conductivity

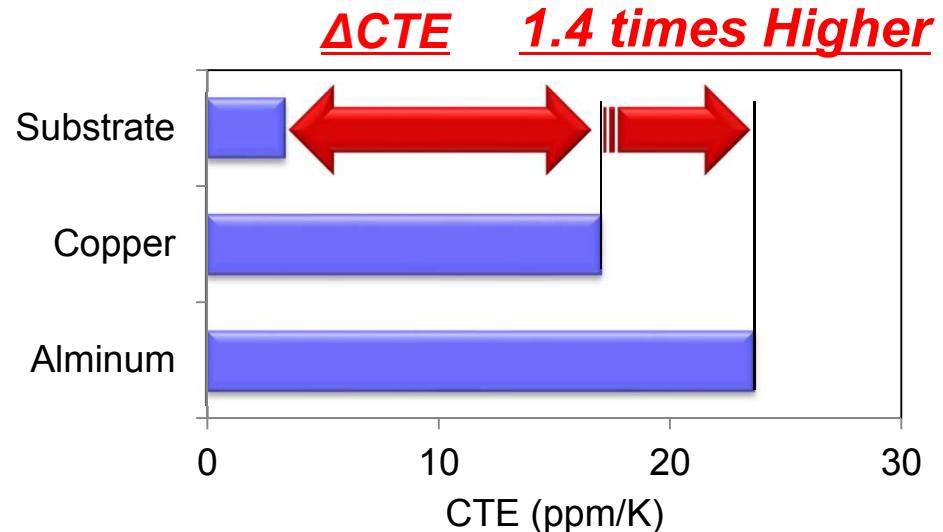


Temperature of semiconductor

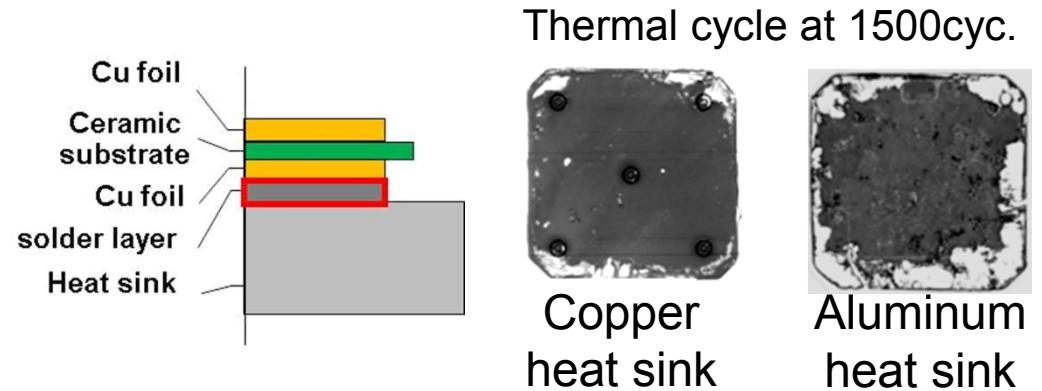


■ Thermal design and high strength joint layer are needed

II. Large CTE mismatch

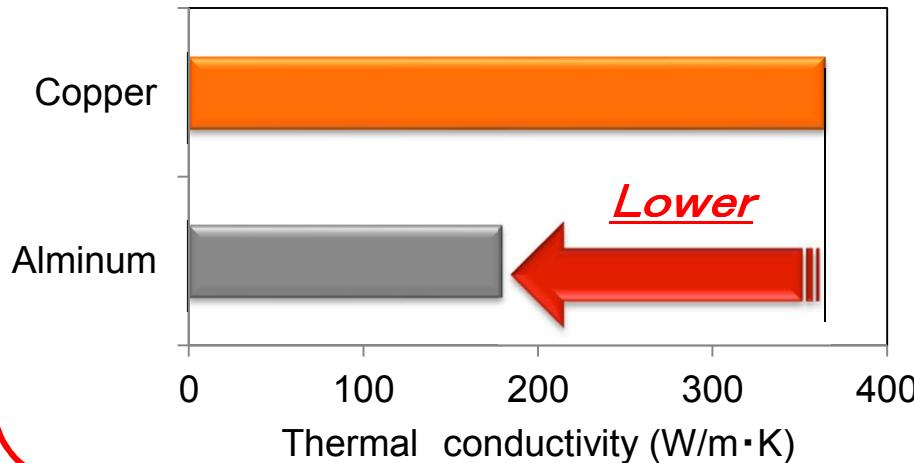


Reliability of joint layer

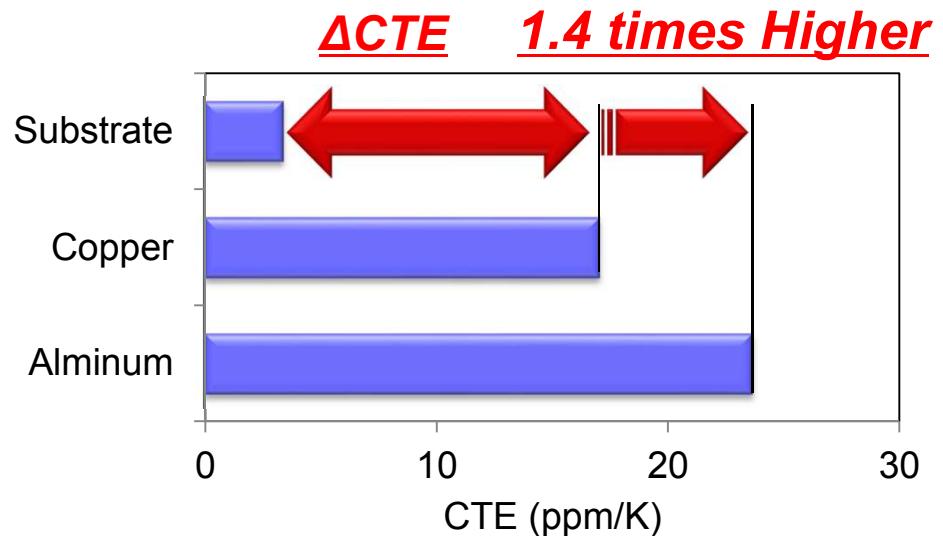


1. Background of Development
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I. Low thermal conductivity

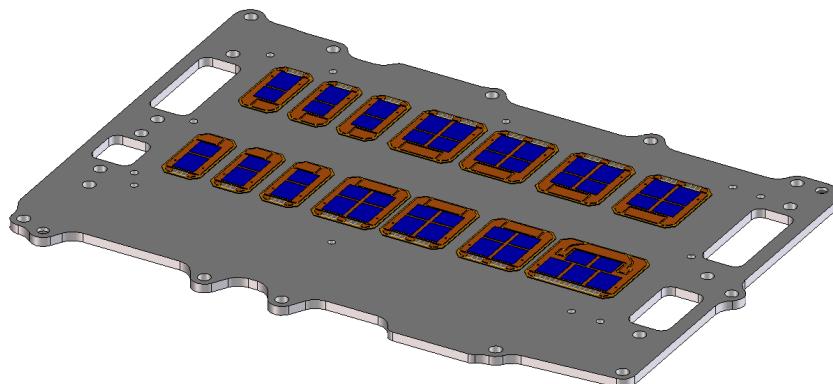


II. Large CTE mismatch

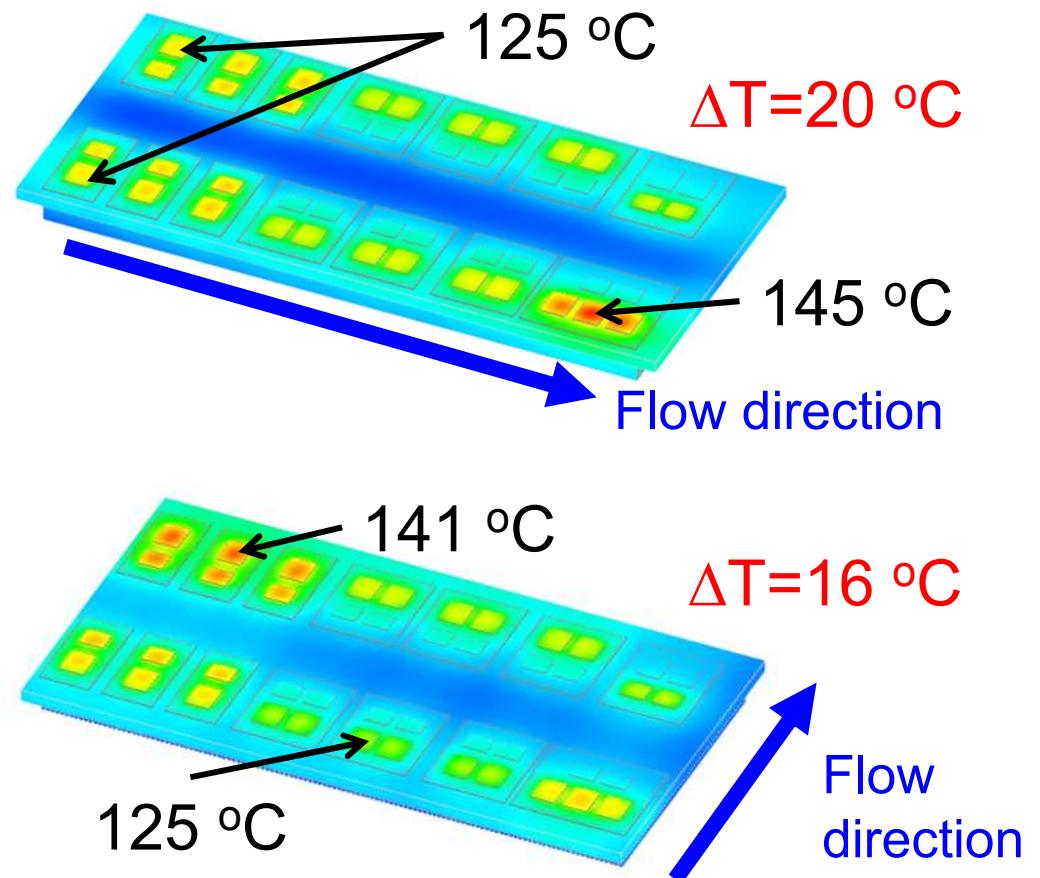


Simulation model (real product)

Size : 320x170 mm
Inlet : 60 °C
Flow speed : 10 l/min.
Chip operation : maximum



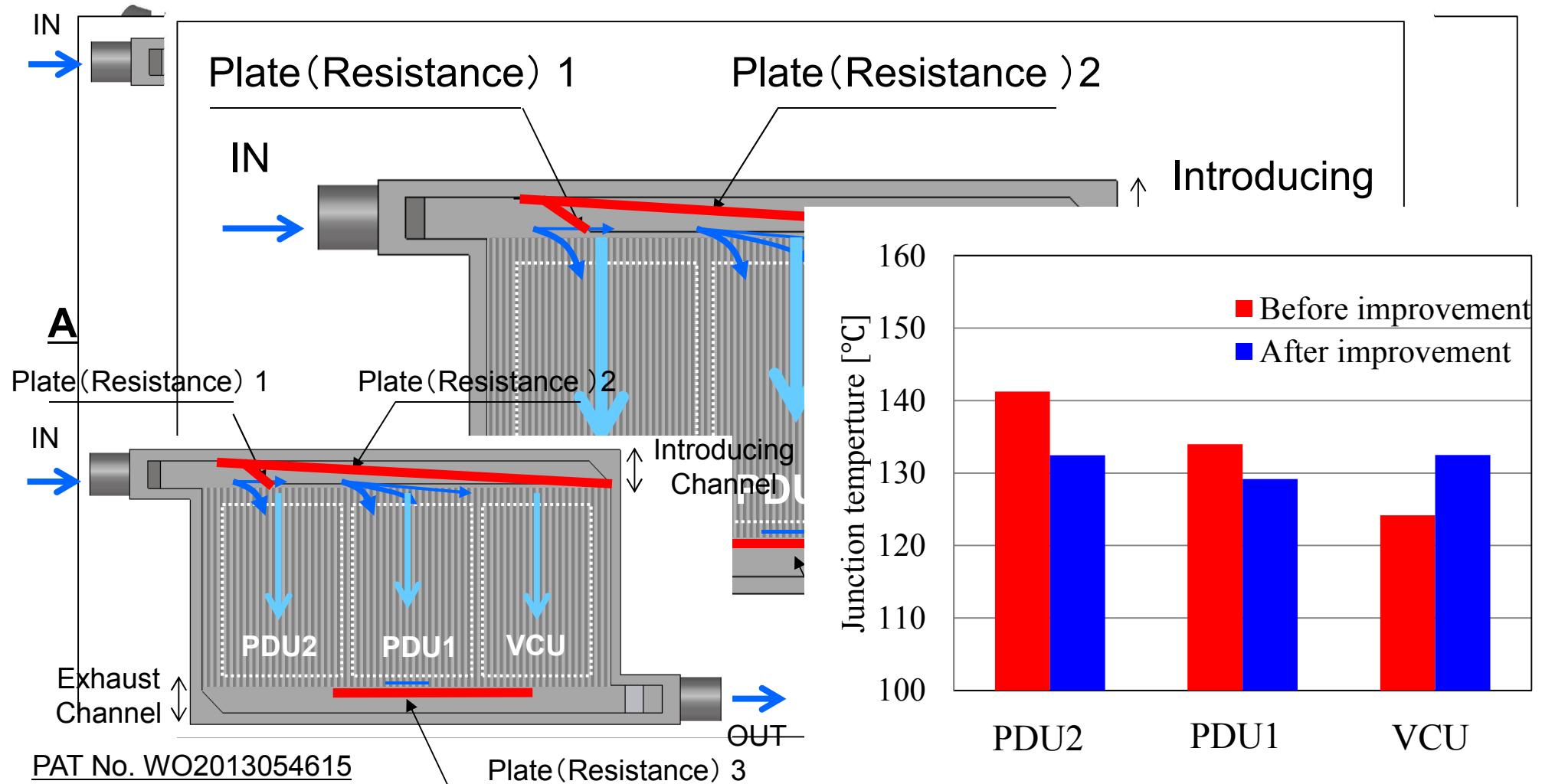
Temperature distribution of coolant



- Optimization is necessary to reduce temperature distribution

Optimization of flow distribution

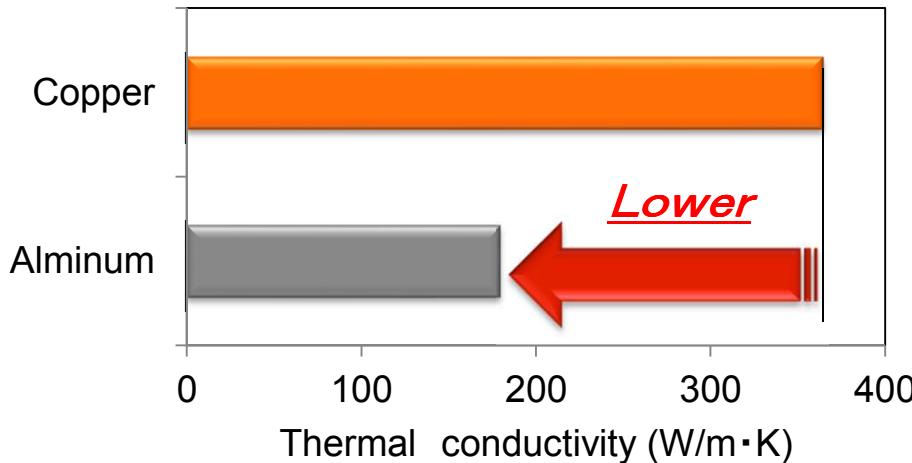
Before Optimization



- With this design, we have a almost the same performance with Aluminum heat sink as Copper heat sink.

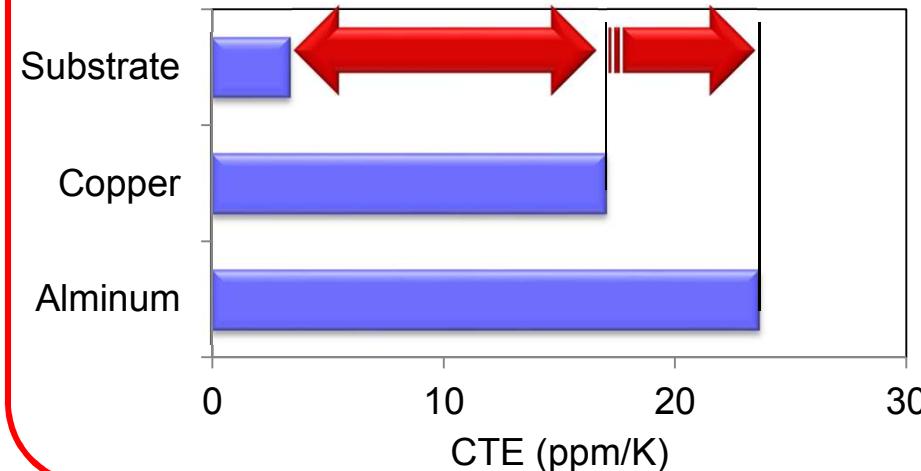
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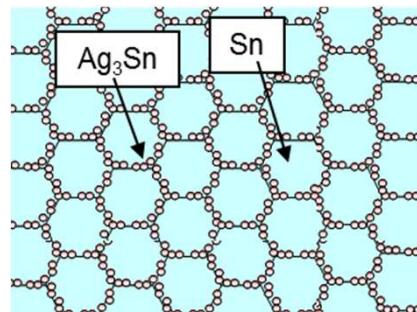
ΔCTE 1.4 times Higher



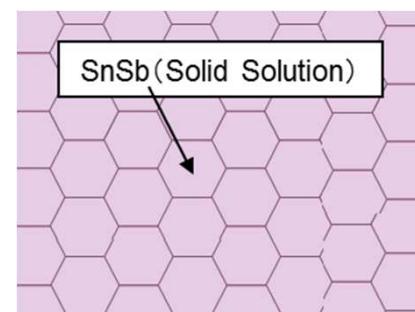
Strengthening Mechanism of Solder Alloy

Aging condition
175 °C
1000 hours

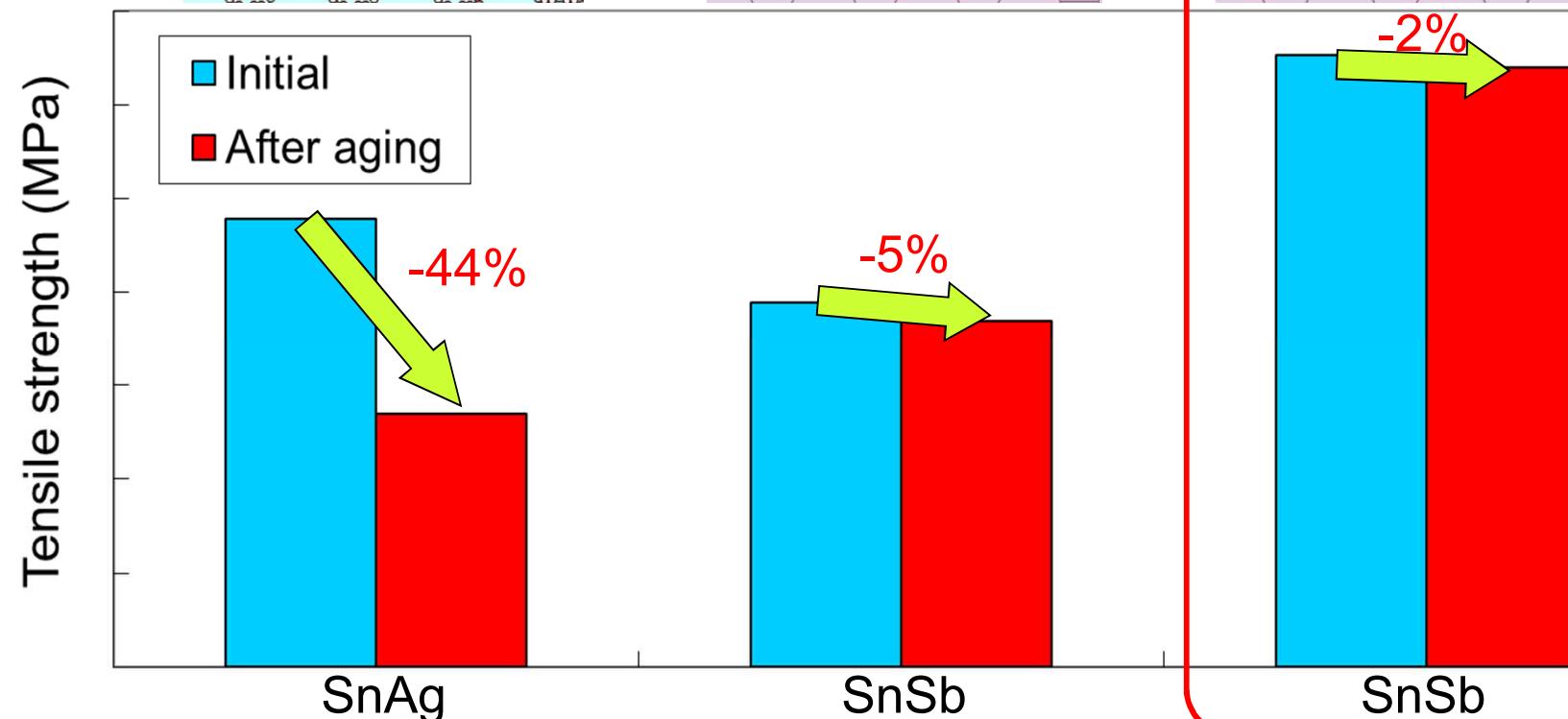
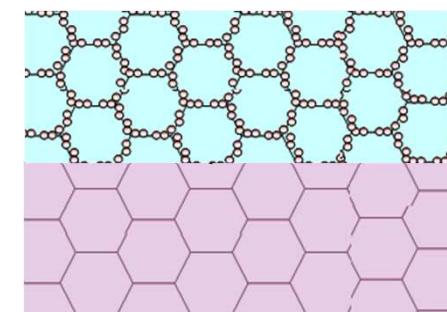
Precipitation Strengthening



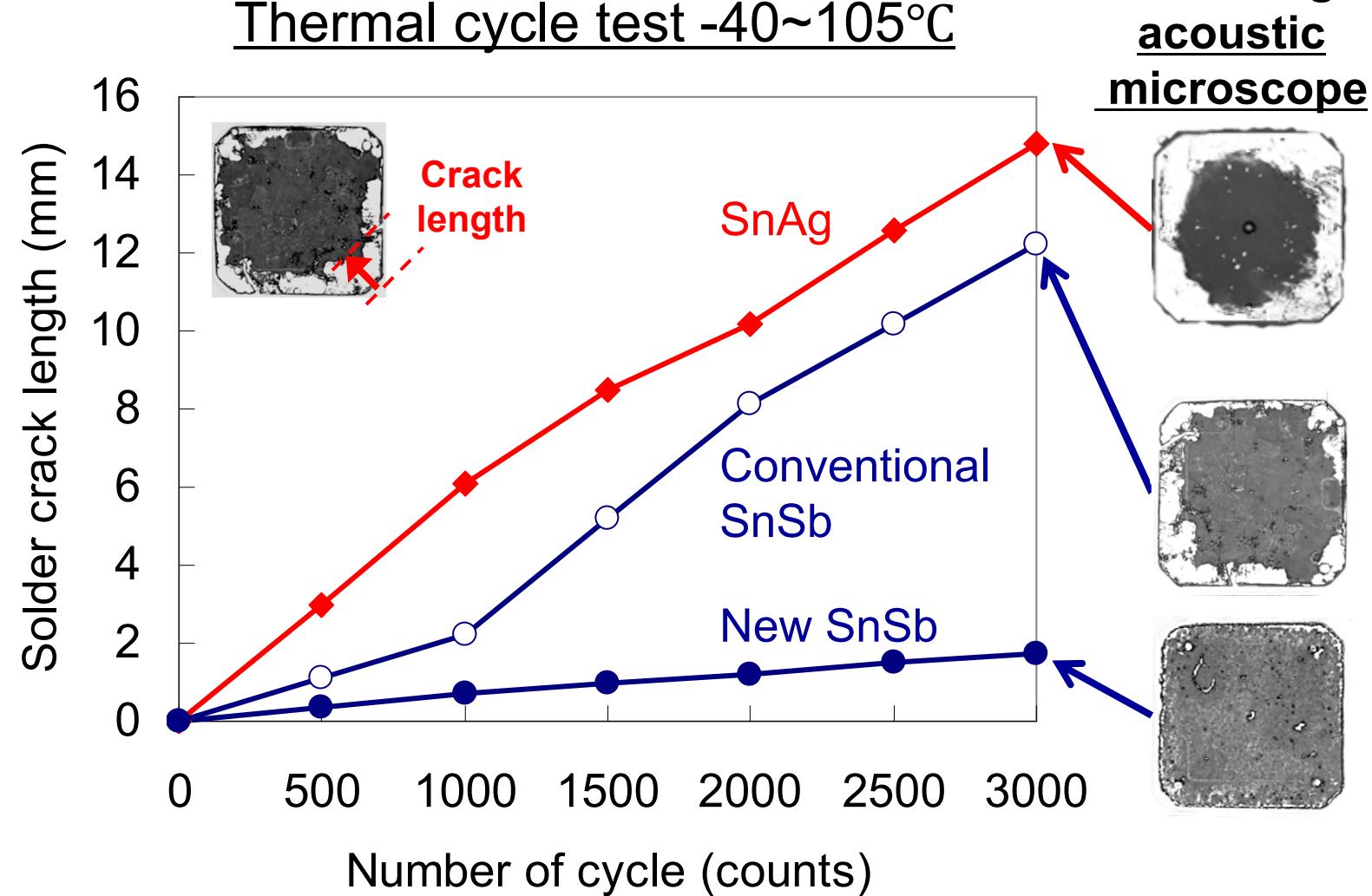
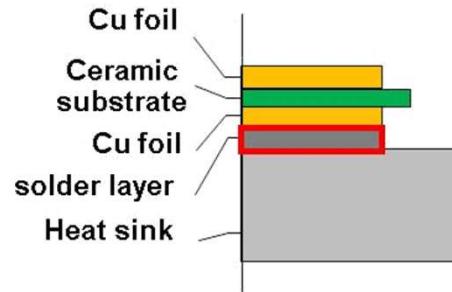
Solid Solution Strengthening



Combination Strengthening

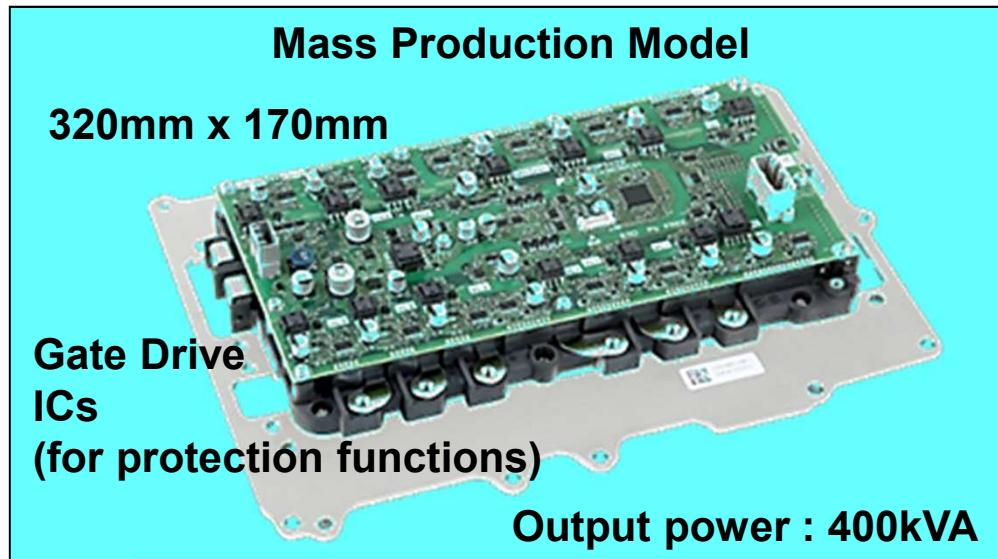


Effect of Thermal Fatigue Characteristics of New Solder

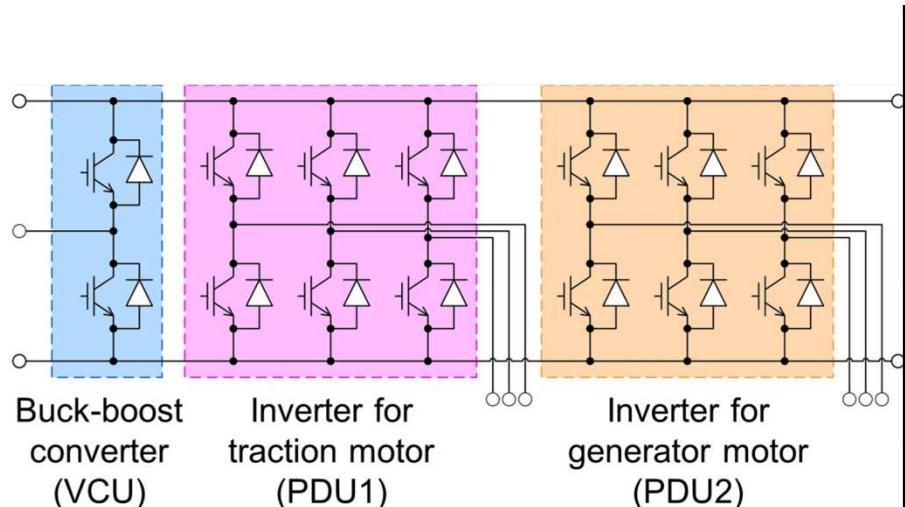
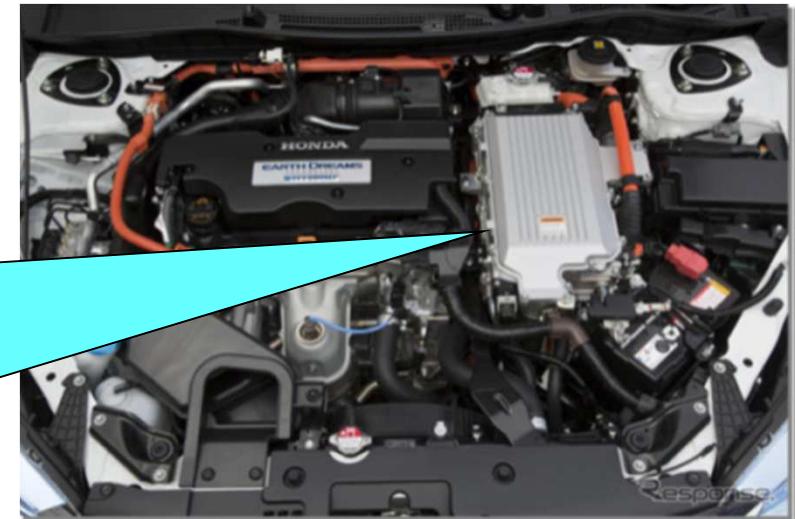


- Achieved 7 times longer lifetime against the general Sn-Ag Solder.

Product Summary of a Newly Developed IPM



Engine Room in hybrid Electric Vehicle



Unit	Specifications
Power Module	14-in-1 unit of IGBT/FWD in total IGBT Output power : 400 kVA (in total)
IGBT chip	Fuji Electric V-series (6th generation) System voltage : 1200 V
Self Protection function	IPM status sensing (temperature, voltage and failure information) and self protection by itself. Information communication with ECU.

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Conclusions

1. Design of Aluminum heat-sink
 - Developed a cooling structure that can be efficiently cooled

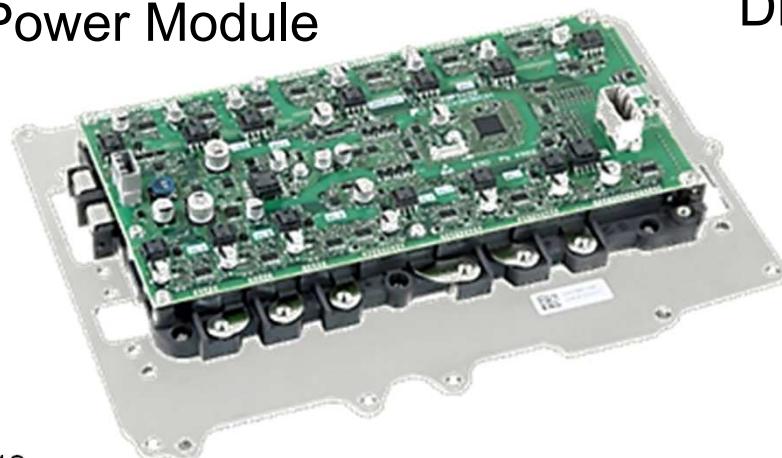
2. Development high reliability solder material
 - Reliability is 7times longer compared with the Sn-Ag solder
 - Achieve a automotive quality used by Aluminum heat-sink

⇒We achieved direct liquid cooling module

- 30% volume, 60% weight reduction compared to products with conventional technologies

Front side

Intelligent Power Module



Back side

Direct Liquid Cooling Fin



Thank you for your attention !



*Four Beautiful Seasons in Matsumoto City
Where Fuji Electric locates*

*Sagrada Familia in Barcelona
Where EVS held*